

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A connection structure between a coaxial connector and a multilayer board comprising:

a casing;

a coaxial connector provided in this casing, and ~~having~~ including a core wire;

a multilayer board provided in the casing, and ~~having~~ including a first signal line pattern, an inner-layer pattern, and a pattern margin provided between an end face of the inner-layer pattern and an end face of the multilayer board;

a transfer board provided in the casing located between ~~[[this]]~~ the multilayer board and the coaxial connector, ~~having the transfer board including~~ a second signal line pattern, a ground pattern, and a pattern margin provided between an end face of the ground pattern and an end face of the transfer board, and the transfer board formed so that the thickness of the transfer board is smaller than the thickness of the multilayer board;

~~[[a]]~~ connecting means for electrically connecting the core wire of the coaxial connector and the second signal line pattern; and

a transmission line that electrically connects the first signal line pattern to the second signal line pattern, and suppresses an electromagnetic field distribution in an inward direction of the multilayer board;

wherein the pattern margin of the transfer board is smaller than the pattern margin of the multilayer board.

2. (Currently Amended) A connection structure between a coaxial connector and a multilayer board comprising:

a casing formed of an upper floor, a lower floor, and a sidewall adjacent to the upper floor;

a coaxial connector provided on the sidewall, and ~~having~~ including a core wire;

a multilayer board provided on the lower floor, and ~~having~~ including a first signal line pattern, an inner-layer pattern, and a pattern margin provided between an end face of the inner-layer pattern and an end face of the multilayer board;

a transfer board provided on the upper floor, and ~~having~~ including a second signal line pattern, a ground pattern, and a pattern margin provided between an end face of the ground pattern and an end face of the transfer board;

[[a]] connecting means for electrically connecting the core wire of the coaxial connector and the second signal line pattern; and

a transmission line that electrically connects the first signal line pattern to the second signal line pattern, and suppresses an electromagnetic field distribution in an inward direction of the multilayer board;

wherein the pattern margin of the transfer board is smaller than the pattern margin of the multilayer board.

3. (Original) A connection structure between a coaxial connector and a multilayer board according to claim 1, wherein the transmission line is a coplanar-type transmission line.

4. (Original) A connection structure between a coaxial connector and a multilayer board according to claim 2, wherein the transmission line is a coplanar-type transmission line.

5. (Original) A connection structure between a coaxial connector and a multilayer board according to claim 1, wherein the multilayer board that has the first signal line pattern includes a microstripline-type transmission line or a coplanar-type transmission line.

6. (Original) A connection structure between a coaxial connector and a multilayer board according to claim 2, wherein the multilayer board that has the first signal line pattern

includes a microstripline-type transmission line or a coplanar-type transmission line.

7. (Currently Amended) A connection structure between a coaxial connector and a multilayer board according to claim 1, wherein the transfer board ~~has a second backside ground pattern, and this second backside ground pattern and the second signal line pattern are electrically connected by use of a via hole formed on the side of the multilayer board~~ includes a top surface layer electrically connected by a via to the ground pattern of the transfer board.

8. (Currently Amended) A connection structure between a coaxial connector and a multilayer board according to claim 2, wherein the transfer board ~~has a second backside ground pattern, and this second backside ground pattern and the second signal line pattern are electrically connected by use of a via hole formed on the side of the multilayer board~~ includes a top surface layer electrically connected by a via to the ground pattern of the transfer board.